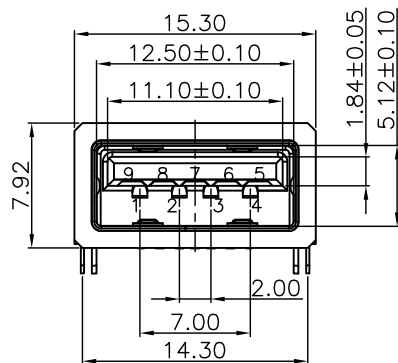


NOTE:

1.MATERIAL:

- 1.1 INSULATOR:PA10T UL94V-0,BLACK
- 1.2 CONTACT:C7025(T=0.25mm)
- 1.3 SHELL:SUS304 (T=0.30mm)

2.ELECTRICAL CHARACTERISTICS:

- 2.1 CONTACT RESISTANCE:30mΩ MAXIMUM
- 2.2 CONTACT CURRENT RATING:1.5A
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE:500 V

R.M.S.

- 2.4 INSULATION RESISTANCE 1000 MEGOHMS MIN
- 2.5 OPERATING TEMPERATURE:-40°C ~ 85°C

3 MECHANICAL CHARACTERISTICS:

- 3.1 MATING FORCE:3.57kg MAX
- 3.2 UNMATED FORCE:1.02kg MIN
- 3.3 DURABILITY:MANDATORY:5,000 CYCLES

4.PLATING

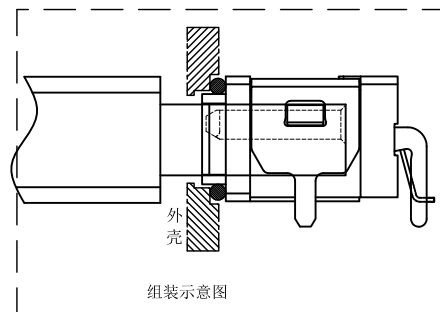
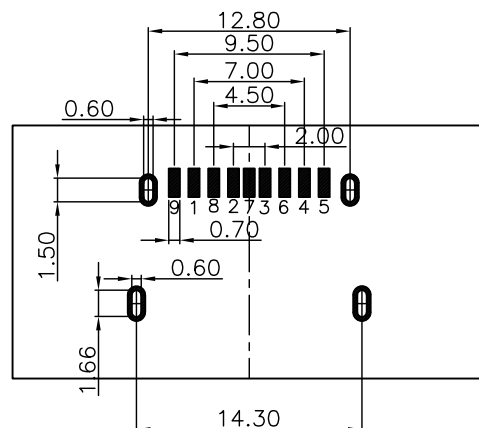
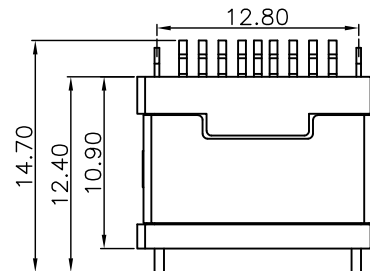
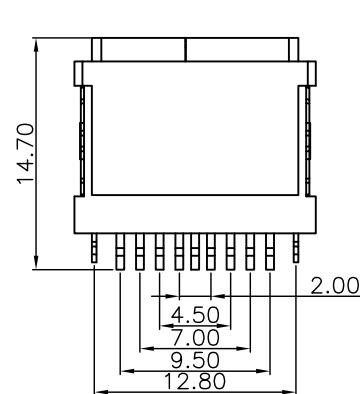
4.1 TERMINAL:

- 30u" MIN. Ni UNDERPLATED OVERALL
- 80u"MIN. Tin PLATED ON SOLDER AREA
- 1u" PLATED ON CONTACT AREA

4.2 SHELL:50u"MIN. Ni PLATED OVERALL

- 5.DESIGN FOR WATERPROOF WITH IPX7(WATER SLOT WITH 1.0MM&30MINUTES)

Pin #	SIGNAL NAME	DESCRIPTION
1	VBUS	POWER
2	D-	USB 2.0 DIFFERENTIAL PAIR
3	D+	DIFFERENTIAL PAIR
4	GND	GROUND FOR POWER RETURN
5	SIdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR
6	SIdA_SSRX+	
7	GND_DRAIN	GROUND FOR SIGNAL RETURN
8	SIdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR
9	SIdA_SSTX+	
Shell	Shield	CONNECTOR METAL SHELL



5	OUTER Shell	1	SUS 304 Ni 50U"	T=0.20mm
4	Inner Shell	1	SUS 304 Ni 50U"	T=0.30mm
3	PLASTIC Shell	1	PA10T (G.F30%)	
2	Contact	9	C7025 Ni 50U" Au1U" Plating Solder area Sn 80-120U"	T=0.25mm
1	Housing	1	PA10T (G.F30%)	
ITEM	PART NAME	Q' TY	FINISH	NOTE

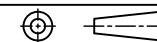


深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X' ±2" X.X" ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

防水USB 3.0 AF 板上型 无柱

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW175-USBA09-124B

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2512081042

SHEET NO.

1 OF 1